* Break-away sections for easier prototyping
2-, 3-, 4-wire configuration:
2-wire: R4=R; R12=R
3-wire (default): R4=DNP; R12=DNP
4-wire: R4=DNP; R12=DNP

Connector J1
It can be used for 2-, 3-, and 4-wire connection of a separate sensor.
2-wire: Use PINs 2 & 3
3-wire: Use PINs 2 & 3 & 4
4-wire: Use PINs 1/2, 4 & 5

NOTE: Break-out section 1 should be physically removed

2-wire: R4=DNP; R12=DNP
3-wire: R4=0R; R12=0R
4-wire: R4=DNP; R12=DNP

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Connector J1
4-wire: R4=DNP; R12=DNP
2-wire: R4=0R; R12=0R

2-, 3-, 4-wire configuration:

GND
VCC

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